



<i>flow</i> PACK 2	1200V/100A
<div style="border: 1px solid black; padding: 5px; margin-bottom: 5px;"> <p style="text-align: center; margin: 0;">Features</p> <ul style="list-style-type: none"> High power flow2 housing Trench Fieldstop Technology IGBT4 Compact and low inductive design </div> <div style="border: 1px solid black; padding: 5px; margin-bottom: 5px;"> <p style="text-align: center; margin: 0;">Target Applications</p> <ul style="list-style-type: none"> Motor Drive Power Generation UPS </div> <div style="border: 1px solid black; padding: 5px;"> <p style="text-align: center; margin: 0;">Types</p> <ul style="list-style-type: none"> V23990-P689-F </div>	<div style="border: 1px solid black; padding: 5px; margin-bottom: 5px;"> <p style="text-align: center; margin: 0;"><i>flow</i> 2 17mm housing</p> </div> <div style="border: 1px solid black; padding: 5px;"> <p style="text-align: center; margin: 0;">Schematic</p> </div>

Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Inverter Switch				
Collector-emitter break down voltage	V_{CE}		1200	V
DC collector current	I_C	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	100	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	300	A
Power dissipation per IGBT	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	270	W
Gate-emitter peak voltage	V_{GE}		±20	V
Short circuit ratings	t_{SC} V_{CC}	$T_j \leq 150\text{ °C}$ $V_{GE} = 15\text{ V}$	10 900	μs V
Maximum Junction Temperature	T_{jmax}		175	°C
Inverter Diode				
Peak Repetitive Reverse Voltage	V_{RRM}		1200	V
DC forward current	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	85	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	200	A
Power dissipation per Diode	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	160	W
Maximum Junction Temperature	T_{jmax}		175	°C



Maximum Ratings

$T_i = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
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Modul Properties

Thermal Properties

Storage temperature	T_{stg}		-40...+125	°C
Operation temperature under switching condition	T_{op}		-40...+($T_{jmax} - 25$)	°C

Insulation Properties

Insulation voltage	V_{is}	DC Test Voltage* $t_p = 2\text{ s}$	4000	V
		AC Voltage $t_p = 1\text{ min}$	2500	V
Creepage distance			min 12,7	mm
Clearance			min 12,7	mm
Competative tracking index	CTI		>200	

* 100 % tested in production



Characteristic Values

Parameter	Symbol	Conditions					Value			Unit	
		V_{GE} [V]	V_{GS} [V]	V_r [V]	V_{CE} [V]	V_{DS} [V]	I_C [A]	I_F [A]	I_D [A]		T_j [°C]

Inverter Switch

Gate emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$				0,0034	25		5	5,8	6,5	V
Collector-emitter saturation voltage	V_{CESat}		15			100	25 150		1,5	1,94 2,35	2,5	V
Collector-emitter cut-off current incl. Diode	I_{CES}		0	1200			25				0,025	mA
Gate-emitter leakage current	I_{GES}		20	0			25				700	nA
Integrated Gate resistor	R_{gint}									2		Ω
Turn-on delay time	$t_{d(on)}$						25 150			104 108		ns
Rise time	t_r						25 150			18 23		
Turn-off delay time	$t_{d(off)}$	$R_{gon} = 8 \Omega$	± 15	600	100		25 150			219 293		
Fall time	t_f	$R_{goff} = 8 \Omega$					25 150			72 111		
Turn-on energy loss per pulse	E_{on}						25 150			4,04 6,73		mWs
Turn-off energy loss per pulse	E_{off}						25 150			5,25 8,77		
Input capacitance	C_{ies}									5540		pF
Output capacitance	C_{oss}	$f = 1 \text{ MHz}$	0	25			25			410		
Reverse transfer capacitance	C_{rss}									320		
Gate charge	Q_G	$V_{CC}=960$	± 15			100	25			480		nC
Thermal resistance chip to heatsink per chip	$R_{th(j-s)}$	Thermal grease thickness $\leq 50\mu\text{m}$ $\lambda = 1 \text{ W/mK}$								0,35		K/W

Inverter Diode

Diode forward voltage	V_F					100	25 150		1	1,99 2,01	2,5	V
Peak reverse recovery current	I_{RRM}						25 150			164 187		A
Reverse recovery time	t_{rr}						25 150			130 294		ns
Reverse recovered charge	Q_{rr}	$R_{gon} = 8 \Omega$	± 15	600	100		25 150			9,32 18,66		μC
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$						25 150			8743 3702		A/ μs
Reverse recovered energy	E_{rec}						25 150			3,87 7,96		mWs
Thermal resistance chip to heatsink per chip	$R_{th(j-s)}$	Thermal grease thickness $\leq 50\mu\text{m}$ $\lambda = 1 \text{ W/mK}$								0,60		K/W

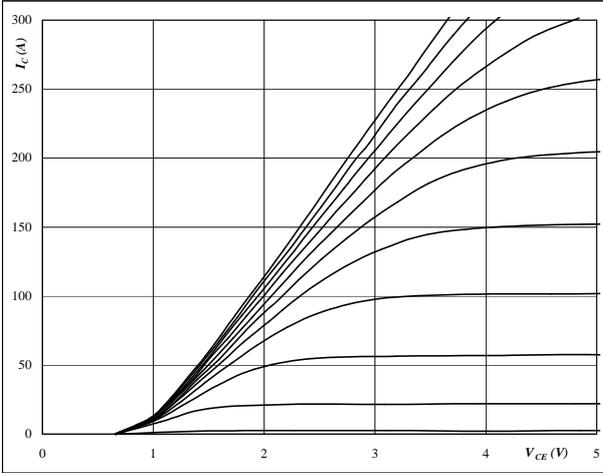


Inverter

Figure 1 Inverter IGBT

Typical output characteristics

$I_C = f(V_{CE})$



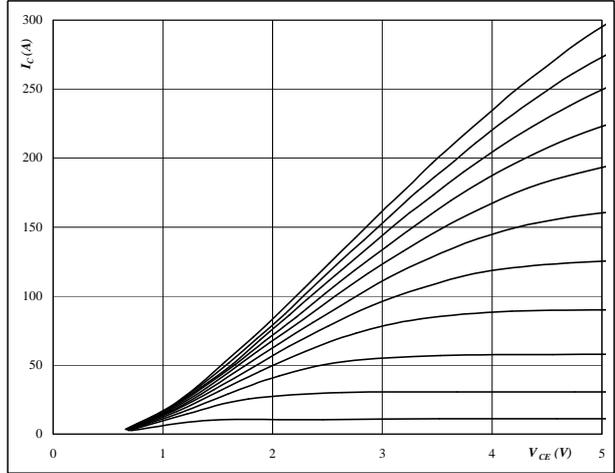
At

$t_p = 250 \mu s$
 $T_j = 25 \text{ }^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

Figure 2 Inverter IGBT

Typical output characteristics

$I_C = f(V_{CE})$



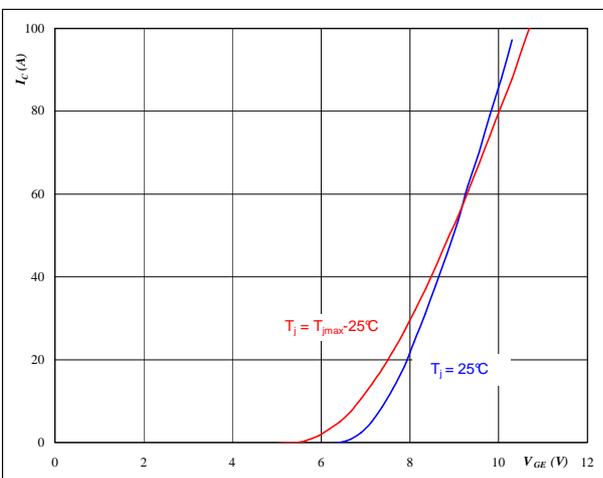
At

$t_p = 250 \mu s$
 $T_j = 150 \text{ }^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

Figure 3 Inverter IGBT

Typical transfer characteristics

$I_C = f(V_{GE})$



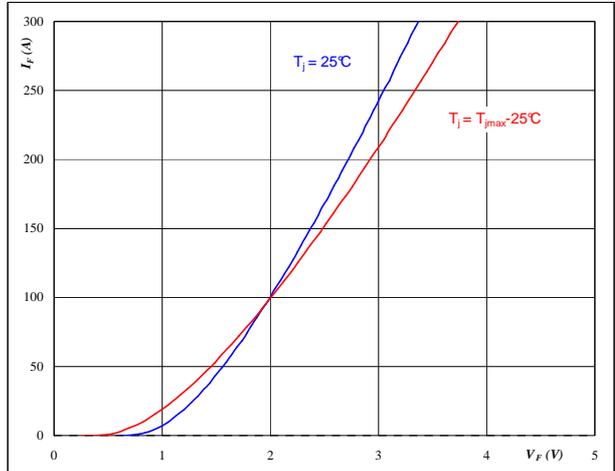
At

$t_p = 250 \mu s$
 $V_{CE} = 10 V$

Figure 4 Inverter FRED

Typical diode forward current as a function of forward voltage

$I_F = f(V_F)$



At

$t_p = 250 \mu s$

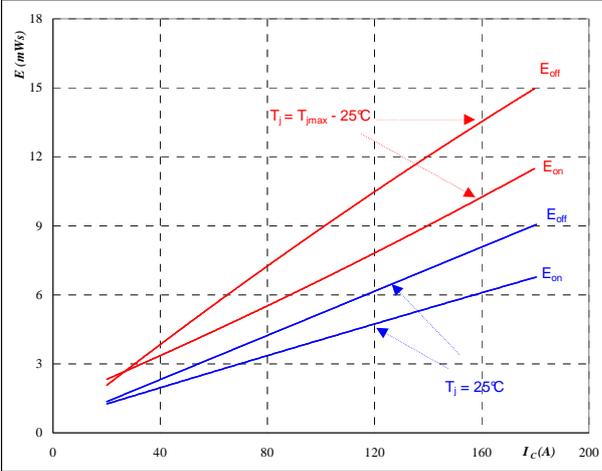


Inverter

Figure 5 Inverter IGBT

Typical switching energy losses as a function of collector current

$E = f(I_C)$



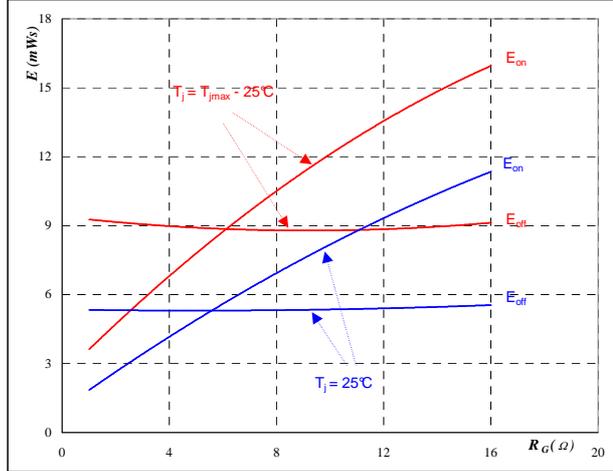
With an inductive load at

- $T_j = 25/150 \text{ } ^\circ\text{C}$
- $V_{CE} = 600 \text{ V}$
- $V_{GE} = \pm 15 \text{ V}$
- $R_{gon} = 4 \text{ } \Omega$
- $R_{goff} = 4 \text{ } \Omega$

Figure 6 Inverter IGBT

Typical switching energy losses as a function of gate resistor

$E = f(R_G)$



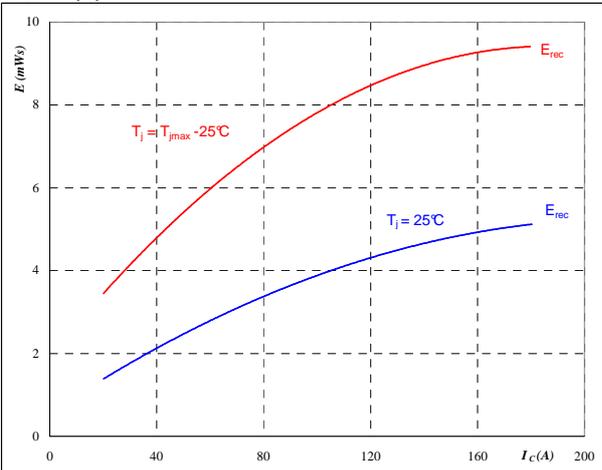
With an inductive load at

- $T_j = 25/150 \text{ } ^\circ\text{C}$
- $V_{CE} = 600 \text{ V}$
- $V_{GE} = \pm 15 \text{ V}$
- $I_C = 100 \text{ A}$

Figure 7 Inverter IGBT

Typical reverse recovery energy loss as a function of collector current

$E_{rec} = f(I_C)$



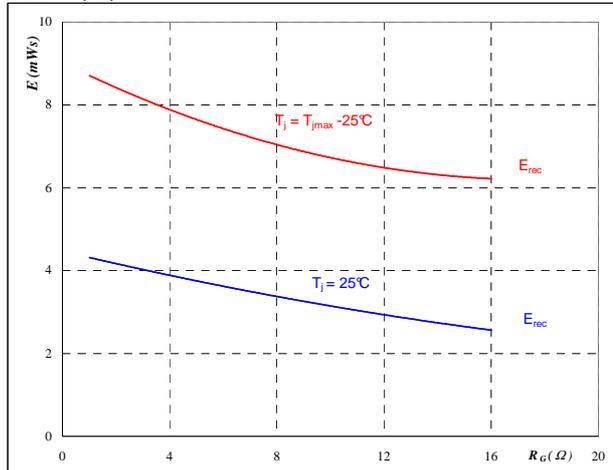
With an inductive load at

- $T_j = 25/150 \text{ } ^\circ\text{C}$
- $V_{CE} = 600 \text{ V}$
- $V_{GE} = \pm 15 \text{ V}$
- $R_{gon} = 4 \text{ } \Omega$

Figure 8 Inverter IGBT

Typical reverse recovery energy loss as a function of gate resistor

$E_{rec} = f(R_G)$



With an inductive load at

- $T_j = 25/150 \text{ } ^\circ\text{C}$
- $V_{CE} = 600 \text{ V}$
- $V_{GE} = \pm 15 \text{ V}$
- $I_C = 100 \text{ A}$

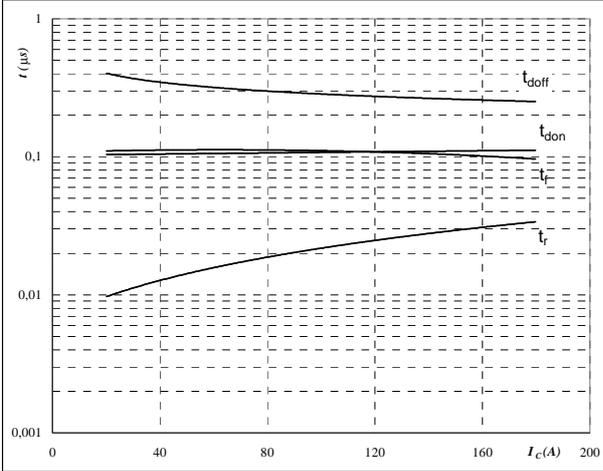


Inverter

Figure 9 Inverter IGBT

Typical switching times as a function of collector current

$t = f(I_C)$



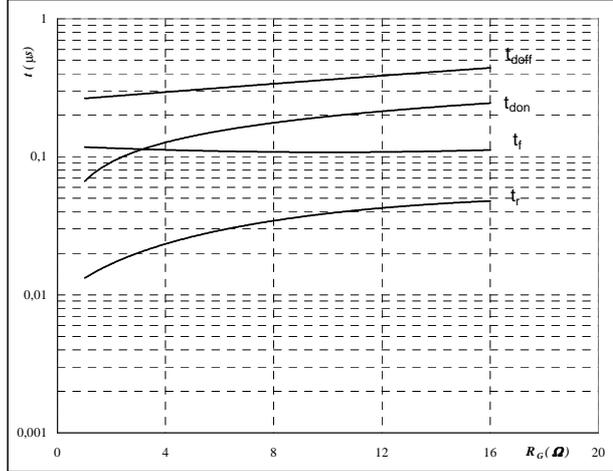
With an inductive load at

- $T_j = 150 \text{ } ^\circ\text{C}$
- $V_{CE} = 600 \text{ V}$
- $V_{GE} = \pm 15 \text{ V}$
- $R_{gon} = 4 \text{ } \Omega$
- $R_{goff} = 4 \text{ } \Omega$

Figure 10 Inverter IGBT

Typical switching times as a function of gate resistor

$t = f(R_G)$



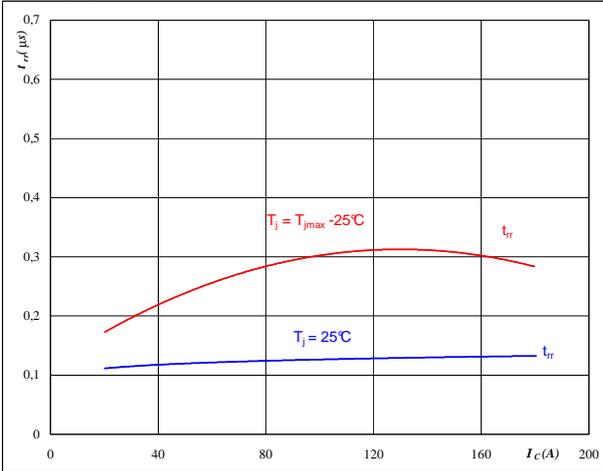
With an inductive load at

- $T_j = 150 \text{ } ^\circ\text{C}$
- $V_{CE} = 600 \text{ V}$
- $V_{GE} = \pm 15 \text{ V}$
- $I_C = 100 \text{ A}$

Figure 11 Inverter FRED

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$



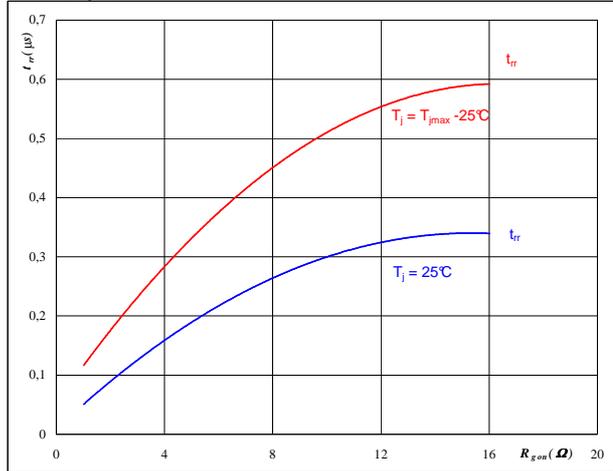
At

- $T_j = 25/150 \text{ } ^\circ\text{C}$
- $V_{CE} = 600 \text{ V}$
- $V_{GE} = \pm 15 \text{ V}$
- $R_{gon} = 4 \text{ } \Omega$

Figure 12 Inverter FRED

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



At

- $T_j = 25/150 \text{ } ^\circ\text{C}$
- $V_R = 600 \text{ V}$
- $I_F = 100 \text{ A}$
- $V_{GE} = \pm 15 \text{ V}$

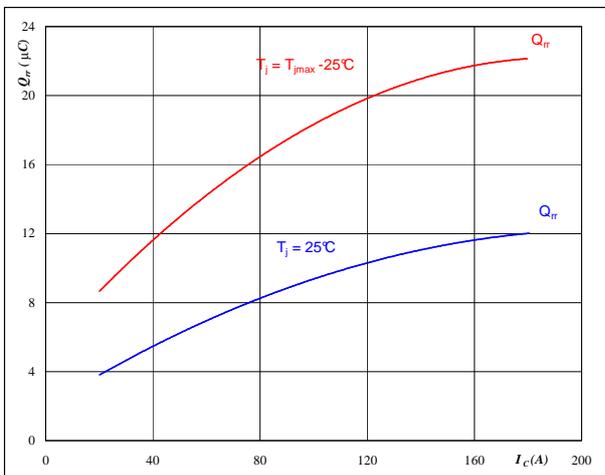


Inverter

Figure 13 Inverter FRED

Typical reverse recovery charge as a function of collector current

$$Q_{rr} = f(I_C)$$



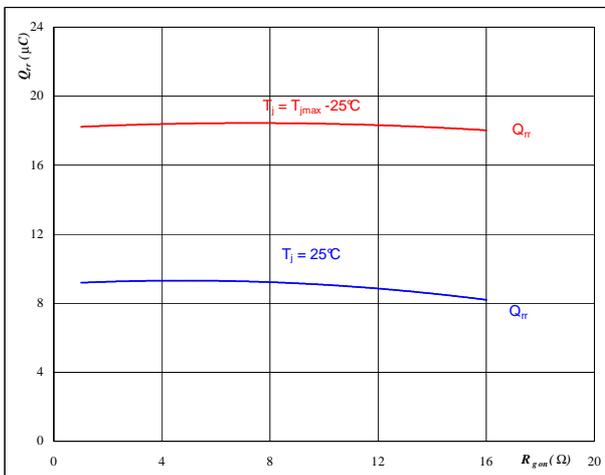
At

$T_j =$	25/150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	4	Ω

Figure 14 Inverter FRED

Typical reverse recovery charge as a function of IGBT turn on gate resistor

$$Q_{rr} = f(R_{gon})$$



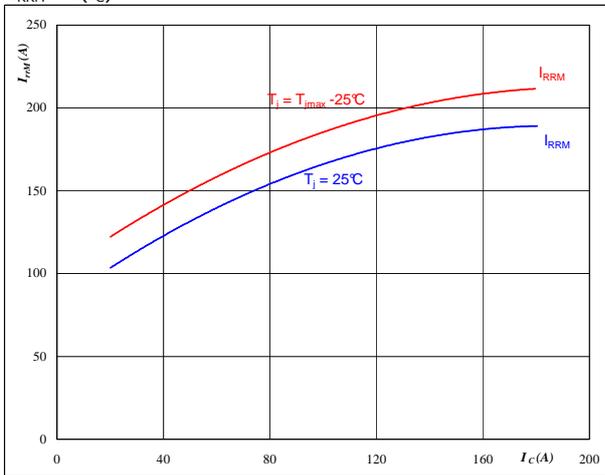
At

$T_j =$	25/150	°C
$V_R =$	600	V
$I_F =$	100	A
$V_{GE} =$	±15	V

Figure 15 Inverter FRED

Typical reverse recovery current as a function of collector current

$$I_{RRM} = f(I_C)$$



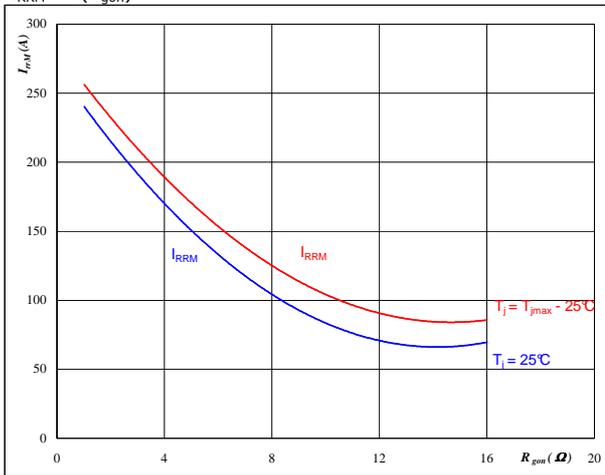
At

$T_j =$	25/150	°C
$V_{CE} =$	600	V
$V_{GE} =$	±15	V
$R_{gon} =$	4	Ω

Figure 16 Inverter FRED

Typical reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RRM} = f(R_{gon})$$



At

$T_j =$	25/150	°C
$V_R =$	600	V
$I_F =$	100	A
$V_{GE} =$	±15	V

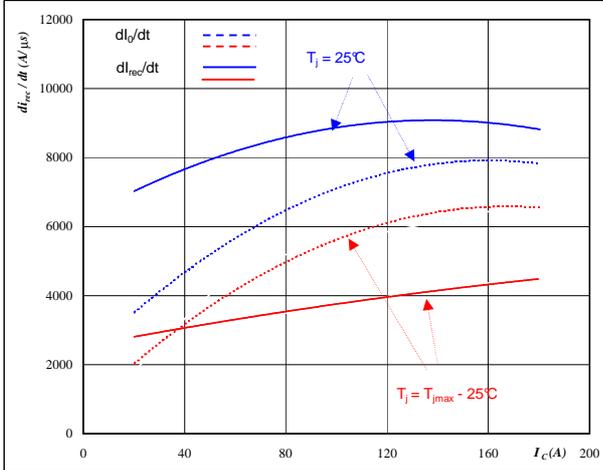


Inverter

Figure 17 Inverter FRED

Typical rate of fall of forward and reverse recovery current as a function of collector current

$$dI_o/dt, dI_{rec}/dt = f(I_c)$$

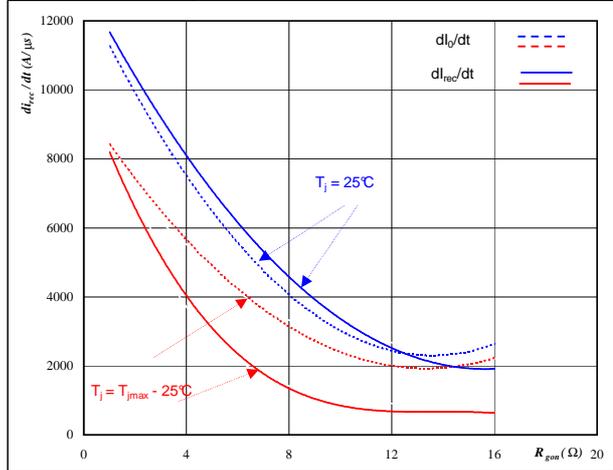


At
 $T_j = 25/150 \text{ } ^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 4 \text{ } \Omega$

Figure 18 Inverter FRED

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

$$dI_o/dt, dI_{rec}/dt = f(R_{gon})$$

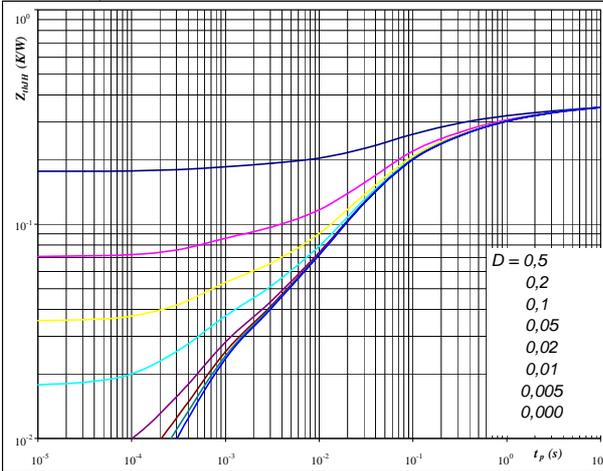


At
 $T_j = 25/150 \text{ } ^\circ\text{C}$
 $V_R = 600 \text{ V}$
 $I_F = 100 \text{ A}$
 $V_{GE} = \pm 15 \text{ V}$

Figure 19 Inverter IGBT

IGBT transient thermal impedance as a function of pulse width

$$Z_{thJH} = f(t_p)$$



At
 $D = t_p / T$
 $R_{thJH} = 0,35 \text{ K/W}$

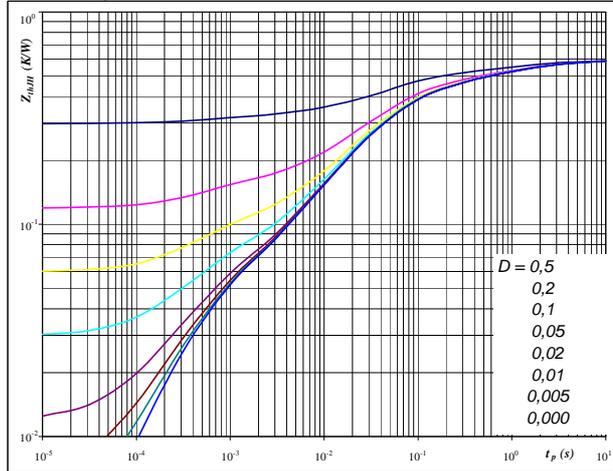
IGBT thermal model values

R (C/W)	Tau (s)
0,06	3,1E+00
0,09	4,1E-01
0,14	6,1E-02
0,05	1,2E-02
0,02	7,0E-04

Figure 20 Inverter FRED

FRED transient thermal impedance as a function of pulse width

$$Z_{thJH} = f(t_p)$$



At
 $D = t_p / T$
 $R_{thJH} = 0,60 \text{ K/W}$

FRED thermal model values

R (C/W)	Tau (s)
0,03	9,1E+00
0,10	1,3E+00
0,14	1,7E-01
0,25	3,1E-02
0,04	4,4E-03
0,04	4,5E-04

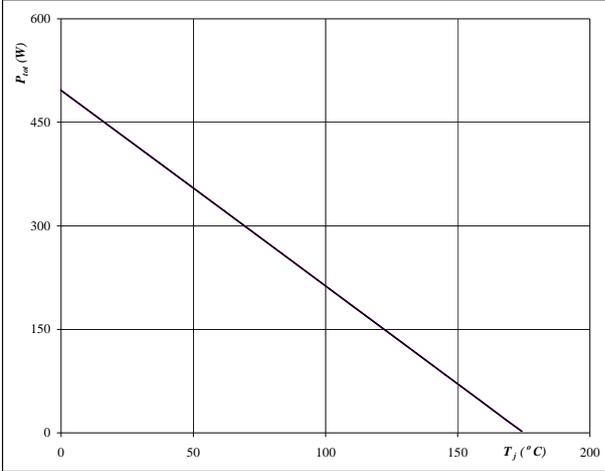


Inverter

Figure 21 Inverter IGBT

Power dissipation as a function of heatsink temperature

$P_{tot} = f(T_j)$

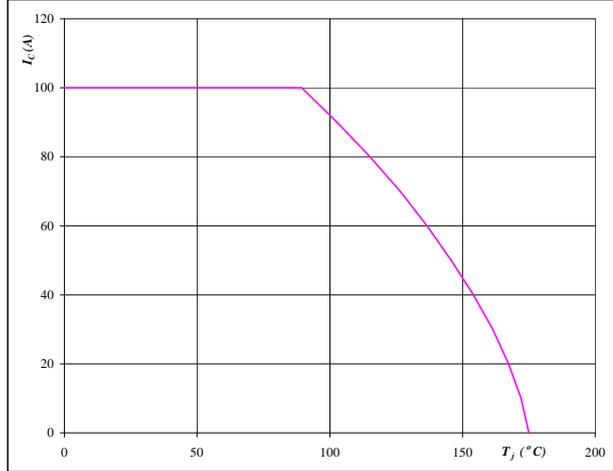


At
T_j = 175 °C

Figure 22 Inverter IGBT

Collector current as a function of heatsink temperature

$I_C = f(T_j)$

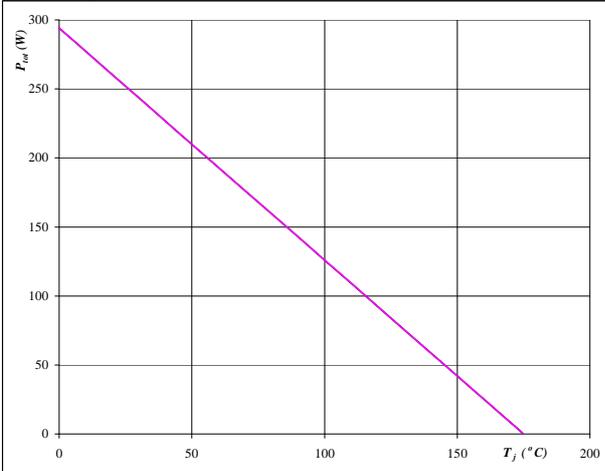


At
T_j = 175 °C
V_{GE} = 15 V

Figure 23 Inverter FRED

Power dissipation as a function of heatsink temperature

$P_{tot} = f(T_j)$

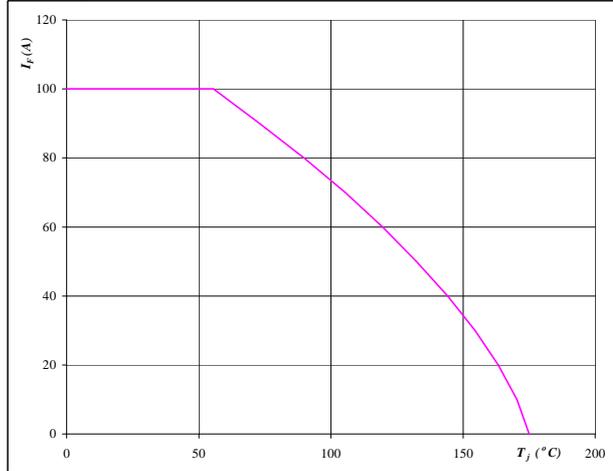


At
T_j = 175 °C

Figure 24 Inverter FRED

Forward current as a function of heatsink temperature

$I_F = f(T_j)$



At
T_j = 175 °C

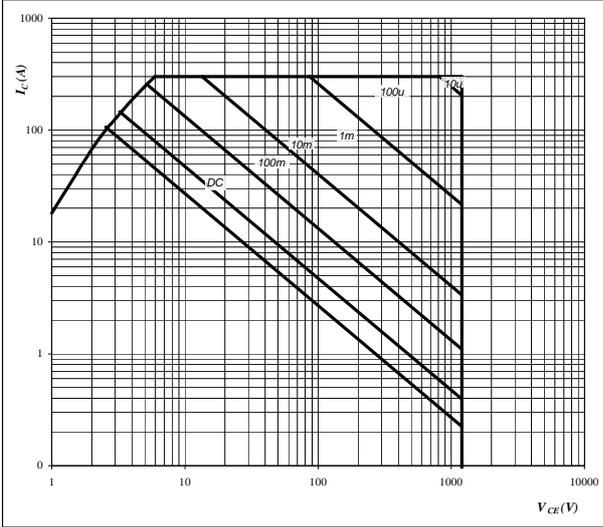


Inverter

Figure 25 Inverter IGBT

Safe operating area as a function of collector-emitter voltage

$I_C = f(V_{CE})$

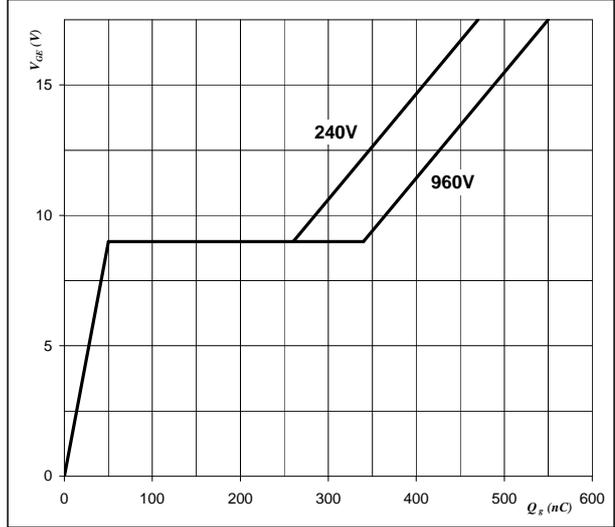


At
 D = single pulse
 Th = 80 °C
 V_{GE} = ±15 V
 T_j = T_{jmax}

Figure 26 Inverter IGBT

Gate voltage vs Gate charge

$V_{GE} = f(Q_g)$



At
 I_C = 100 A



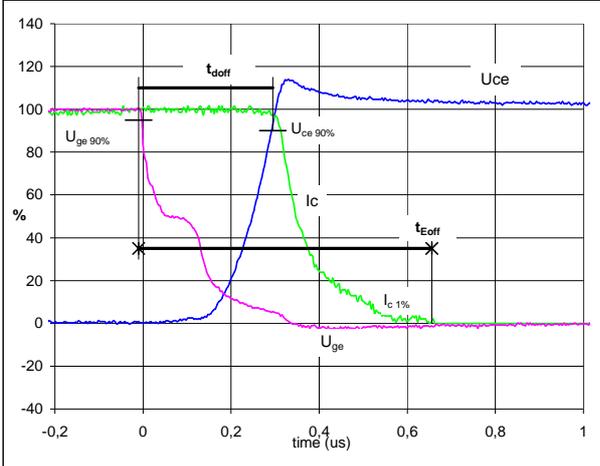
Switching Definitions Inverter

General conditions

T_j	=	150 °C
R_{gon}	=	4 Ω
R_{goff}	=	4 Ω

Figure 1 Inverter IGBT

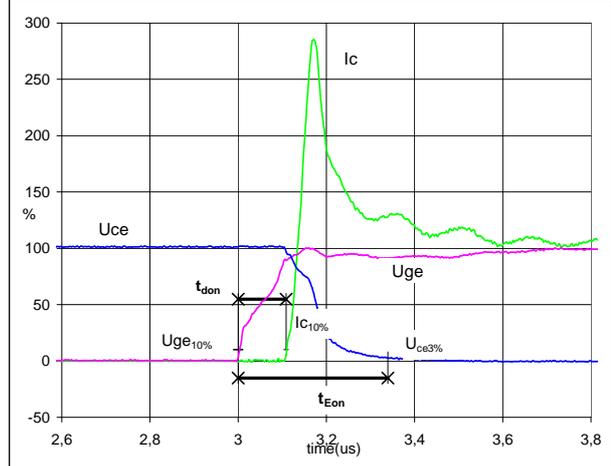
Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff}
 (t_{Eoff} = integrating time for E_{off})



V_{GE} (0%) =	-15	V
V_{GE} (100%) =	15	V
V_C (100%) =	600	V
I_C (100%) =	100	A
t_{doff} =	0,29	μs
t_{Eoff} =	0,67	μs

Figure 2 Inverter IGBT

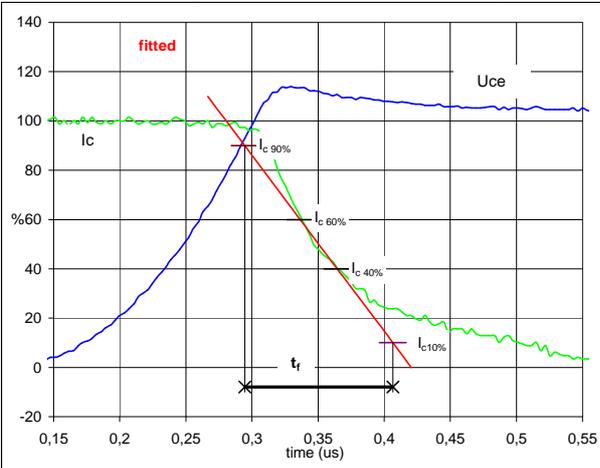
Turn-on Switching Waveforms & definition of t_{don} , t_{Eon}
 (t_{Eon} = integrating time for E_{on})



V_{GE} (0%) =	-15	V
V_{GE} (100%) =	15	V
V_C (100%) =	600	V
I_C (100%) =	100	A
t_{don} =	0,11	μs
t_{Eon} =	0,34	μs

Figure 3 Inverter IGBT

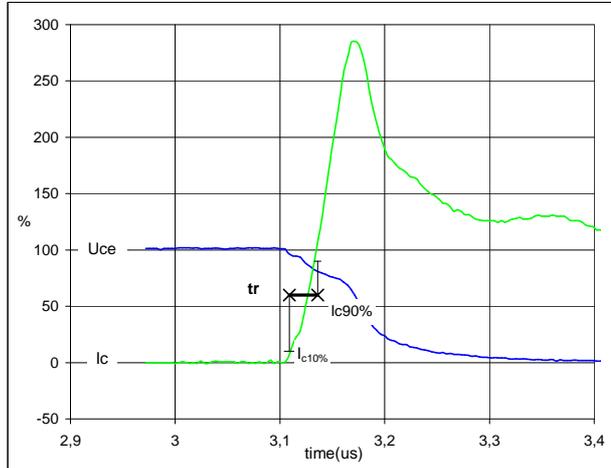
Turn-off Switching Waveforms & definition of t_f



V_C (100%) =	600	V
I_C (100%) =	100	A
t_f =	0,11	μs

Figure 4 Inverter IGBT

Turn-on Switching Waveforms & definition of t_r

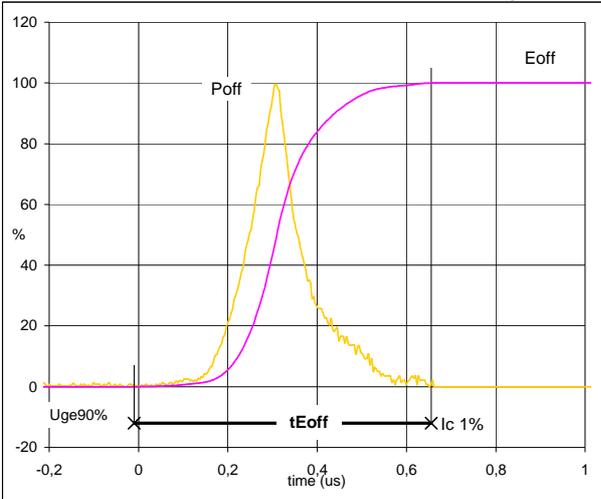


V_C (100%) =	600	V
I_C (100%) =	100	A
t_r =	0,02	μs



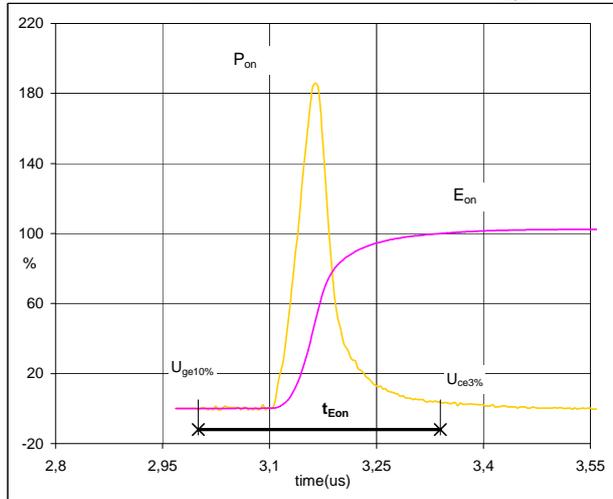
Switching Definitions Inverter

Figure 5 Inverter IGBT
Turn-off Switching Waveforms & definition of t_{Eoff}



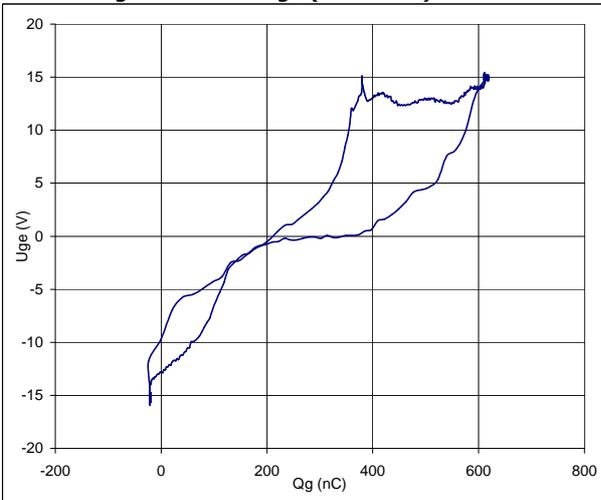
$P_{off} (100\%) = 60,25 \text{ kW}$
 $E_{off} (100\%) = 8,77 \text{ mJ}$
 $t_{Eoff} = 0,67 \text{ } \mu\text{s}$

Figure 6 Inverter IGBT
Turn-on Switching Waveforms & definition of t_{Eon}



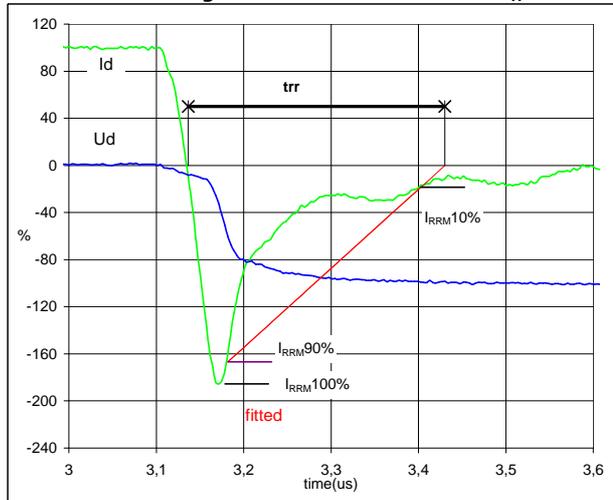
$P_{on} (100\%) = 60,25 \text{ kW}$
 $E_{on} (100\%) = 6,73 \text{ mJ}$
 $t_{Eon} = 0,34 \text{ } \mu\text{s}$

Figure 7 Inverter FRED
Gate voltage vs Gate charge (measured)



$V_{GEoff} = -15 \text{ V}$
 $V_{GEon} = 15 \text{ V}$
 $V_C (100\%) = 600 \text{ V}$
 $I_C (100\%) = 100 \text{ A}$
 $Q_g = 4658,95 \text{ nC}$

Figure 8 Inverter IGBT
Turn-off Switching Waveforms & definition of t_{rr}



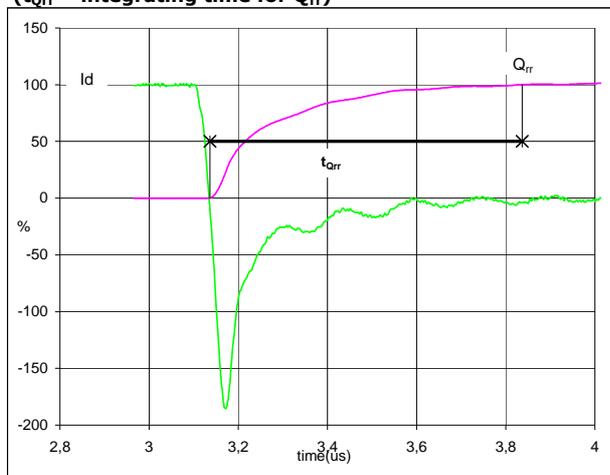
$V_d (100\%) = 600 \text{ V}$
 $I_d (100\%) = 100 \text{ A}$
 $I_{RRM} (100\%) = -187 \text{ A}$
 $t_{rr} = 0,29 \text{ } \mu\text{s}$



Switching Definitions Inverter

Figure 9 Inverter FRED

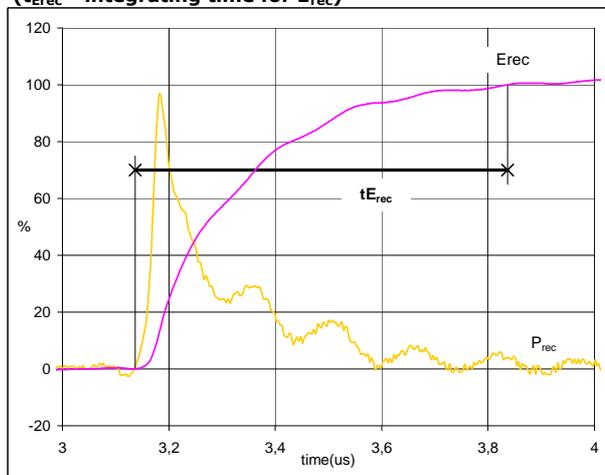
Turn-on Switching Waveforms & definition of t_{Qrr}
 (t_{Qrr} = integrating time for Q_{rr})



I_d (100%) =	100	A
Q_{rr} (100%) =	18,66	μC
t_{Qrr} =	0,70	μs

Figure 10 Inverter FRED

Turn-on Switching Waveforms & definition of t_{Erec}
 (t_{Erec} = integrating time for E_{rec})



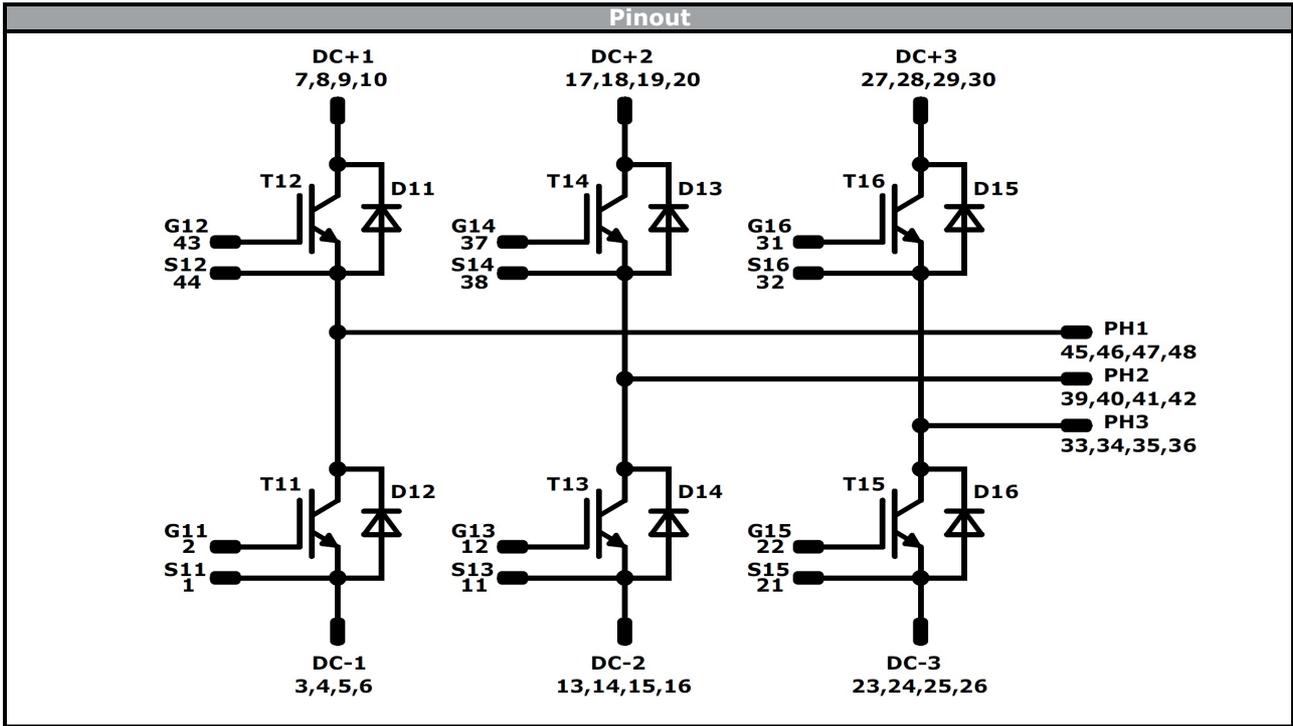
P_{rec} (100%) =	60,25	kW
E_{rec} (100%) =	7,96	mJ
t_{Erec} =	0,70	μs



Ordering Code & Marking						
Version			Ordering Code			
without thermal paste 17mm housing			V23990-P689-F			
with thermal paste 17mm housing			V23990-P689-F-/3/			
			Text	VIN	Date code	Name&Ver
				VIN	WWYY	NNNNNNVV
			UL	Lot	Serial	
			UL	LLLLL	SSSS	
			Datamatrix	Type&Ver	Lot number	Serial
				TTTTTTVV	LLLLL	SSSS
					Date code	
					WWYY	

Outline							
Pin table [mm]				Pin table [mm]			
Pin	X	Y	Function	Pin	X	Y	Function
1	1,2	0	S11	25	57,2	0	DC-3
2	1,2	2,7	G11	26	57,2	2,7	DC-3
3	3,9	0	DC-1	27	65,8	0	DC+3
4	3,9	2,7	DC-1	28	65,8	2,7	DC+3
5	6,6	0	DC-1	29	68,5	0	DC+3
6	6,6	2,7	DC-1	30	68,5	2,7	DC+3
7	15,2	0	DC+1	31	64,1	36	G16
8	15,2	2,7	DC+1	32	61,4	36	S16
9	17,9	0	DC+1	33	58,7	36	Ph3
10	17,9	2,7	DC+1	34	56	36	Ph3
11	26,5	0	S13	35	53,3	36	Ph3
12	26,5	2,7	G13	36	50,6	36	Ph3
13	29,2	0	DC-2	37	38,8	36	G14
14	29,2	2,7	DC-2	38	36,1	36	S14
15	31,9	0	DC-2	39	33,4	36	Ph2
16	31,9	2,7	DC-2	40	30,7	36	Ph2
17	40,5	0	DC+2	41	28	36	Ph2
18	40,5	2,7	DC+2	42	25,3	36	Ph2
19	43,2	0	DC+2	43	13,5	36	G12
20	43,2	2,7	DC+2	44	10,8	36	S12
21	51,8	0	S15	45	8,1	36	Ph1
22	51,8	2,7	G15	46	5,4	36	Ph1
23	54,5	0	DC-3	47	2,7	36	Ph1
24	54,5	2,7	DC-3	48	0	36	Ph1

Tolerance of positions: ±0,15mm at the end of pins
Direction of coordinate axis is only offset without tolerance



Identification

ID	Component	Voltage	Current	Function	Comment
T11 - T16	IGBT	1200	100	Inverter Switch	
D11 - D16	FWD	1200	100	Inverter Diode	

**Packaging instruction**

Standard packaging quantity (SPQ)	36	>SPQ	Standard	<SPQ	Sample
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Handling instruction

Handling instructions for *flow 2* packages see vincotech.com website.

Package data

Package data for *flow 2* packages see vincotech.com website.

UL recognition and file number

This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.



Document No.:	Date:	Modification:	Pages
V23990-P689-F-D2-14	27 Jun. 2017	Logo corrected, SPQ changed	All

Product status definition**DISCLAIMER**

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